National Semiconductor

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100307
Low Power Quint Exclusive OR/NOR Gate

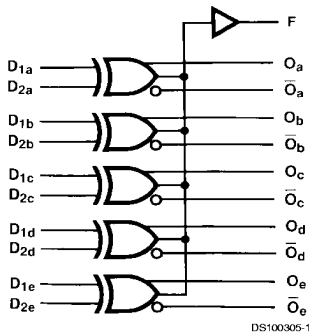
General Description

The 100307 is monolithic quint exclusive-OR/NOR gate. The Function output is the wire-OR of all five exclusive-OR outputs. All inputs have 50 kΩ pull-down resistors.

Features

- Low Power Operation
- 2000V ESD protection
- Pin/function compatible with 100107
- Voltage compensated operating range = −4.2V to −5.7V
- Available to industrial grade temperature range
- Available to Standard Microcircuit Drawing (SMD) 5962-9459001

Logic Symbol



DS100305-1

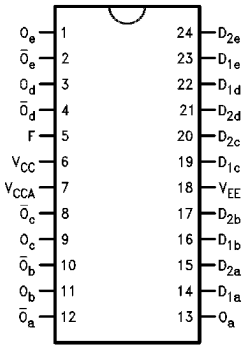
Logic Equation

$F = (D_{1a} \oplus D_{2a}) + (D_{1b} \oplus D_{2b}) + (D_{1c} \oplus D_{2c}) + (D_{1d} \oplus D_{2d}) + (D_{1e} \oplus D_{2e})$.

Pin Names	Description
D_{na}–D_{ne}	Data Inputs
F	Function Output
O_a–O_e	Data Outputs
$\overline{O}_a$–$\overline{O}_e$	Complementary Data Outputs

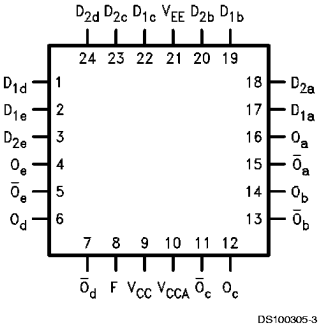
Connection Diagrams

24-Pin DIP



DS100305-2

24-Pin Quad Cerpak



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Absolute Maximum Ratings (Note 1)

If Military/Aerospace specified devices are required, please contact the National Semiconductor Sales Office/ Distributors for availability and specifications.

Above which the useful life may be impaired. (Note 1)

Storage Temperature (T_{STG})	−65°C to +150°C
Maximum Junction Temperature (T_J)	
Ceramic	+175°C
Plastic	+150°C
V_{EE} Pin Potential to Ground Pin	−7.0V to +0.5V
Input Voltage (DC)	V_{EE} to +0.5V
Output Current (DC Output HIGH)	−50 mA
ESD (Note 2)	≥2000V

Recommended Operating Conditions

Case Temperature (T_C)	
Military	−55°C to +125°C
Supply Voltage (V_{EE})	−5.7V to −4.2V

Note 1: Absolute maximum ratings are those values beyond which the device may be damaged or have its useful life impaired. Functional operation under these conditions is not implied.

Note 2: ESD testing conforms to MIL-STD-883, Method 3015.

Military Version DC Electrical Characteristics

V_{EE} = −4.2V to −5.7V, V_{CC} = V_{CCA} = GND, T_C = −55°C to +125°C

Symbol	Parameter	Min	Max	Units	T_C	Conditions		Notes
V_{OH}	Output HIGH Voltage	−1025	−870	mV	0°C to +125°C	V_{IN} = V_{IH} (Max) or V_{IL} (Min)	Loading with 50Ω to −2.0V	1, 2, 3
		−1085	−870	mV	−55°C			
V_{OL}	Output LOW Voltage	−1830	−1620	mV	0°C to +125°C			
		−1830	−1555	mV	−55°C			
V_{OHC}	Output HIGH Voltage	−1035		mV	0°C to +125°C	V_{IN} = V_{IH} (Min) or V_{IL} (Max)	Loading with 50Ω0 to −2.0V	1, 2, 3
		−1085		mV	−55°C			
V_{OLC}	Output LOW Voltage		−1610	mV	0°C to +125°C			
			−1555	mV	−55°C			
V_{IH}	Input HIGH Voltage	−1165	−870	mV	−55°C +125°C	Guaranteed HIGH Signal for All Inputs		1, 2, 3, 4
V_{IL}	Input LOW Voltage	−1830	−1475	mV	−55°C to +125°C	Guaranteed LOW Signal for All Inputs		1, 2, 3,4
I_{IL}	Input LOW Current	0.50		µA	−55°C to +125°C	V_{EE} = −4.2V V_{IN} = V_{IL} (Min)		1, 2, 3
I_{IH}	Input High Current							
	D_{2a}–D_{2e}		250	µA	0°C to			
	D_{1a}–D_{1e}		350		+125°C	V_{EE} = −5.7V		1, 2, 3
	D_{2a}–D_{2e}		350	µA	−55°C	V_{IN} = V_{IH} (Max)		
	D_{1a}–D_{1e}		500					
I_{EE}	Power Supply Current	−75	−25	mA	−55°C to +125°C	Inputs Open		1, 2, 3

Note 3: F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals −55°C), then testing immediately without allowing for the junction temperature to stabilize due to heat dissipation after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.

Note 4: Screen tested 100% on each device at −55°C, +25°C, and +125°C, Subgroups 1, 2 3, 7, and 8.

Note 5: Sample tested (Method 5005, Table I) on each manufactured lot at −55°C, +25°C, and +125°C, Subgroups A1, 2, 3, 7, and 8.

Note 6: Guaranteed by applying specified input condition and testing V_{OH}/V_{OL}.

AC Electrical Characteristics

V_{EE} = −4.2V to −5.7V, V_{CC} = V_{CCA} = GND

Symbol	Parameter	T_C = −55°C		T_C = +25°C		T_C = +125°C		Units	Conditions	Notes
		Min	Max	Min	Max	Min	Max			
t_{PLH} t_{PHL}	Propagation Delay D_{2a}–D_{2e} to O, $\overline{O}$	0.30	2.10	0.40	1.90	0.40	2.40	ns	*Figures 1, 2*	1, 2, 3
t_{PLH} t_{PHL}	Propagation Delay D_{1a}–D_{1e} to O, $\overline{O}$	0.30	1.90	0.40	1.80	0.40	2.20	ns		
t_{PLH} t_{PHL}	Propagation Delay Data to F	0.80	2.90	0.90	2.80	0.90	3.40	ns		
t_{TLH} t_{THL}	Transition Time 20% to 80%, 80% to 20%	0.20	1.70	0.30	1.60	0.20	1.70	ns		4

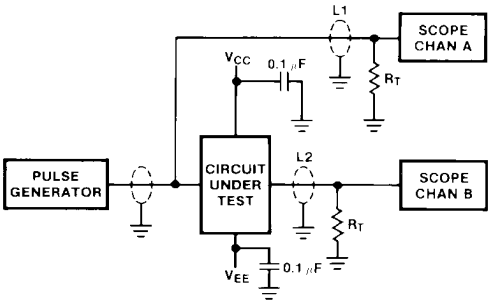
Note 7: F100K 300 Series cold temperature testing is performed by temperature soaking (to guarantee junction temperature equals −55°C), then testing immediately after power-up. This provides "cold start" specs which can be considered a worst case condition at cold temperatures.

Note 8: Screen tested 100% on each device at +25°C temperature only, Subgroup A9.

Note 9: Sample tested (Method 5005, Table I) on each mfg. lot at +25°C, Subgroup A9, and at +125°C and −55°C temperatures, Subgroups A10 and A11.

Note 10: Not tested at +25°C, +125°C, and −55°C temperature (design characterization data).

Test Circuitry



Notes:
V_{CC}, V_{CCA} = +2V, V_{EE} = −2.5V
L1 and L2 = equal length 50Ω impedance lines
R_T = 50Ω terminator internal to scope
Decoupling 0.1 µF from GND to V_{CC} and V_{EE}
All unused outputs are loaded with 50Ω to GND
C_L = Fixture and stray capacitance ≤ 3 pF

FIGURE 1. AC Test Circuit

Switching Waveforms

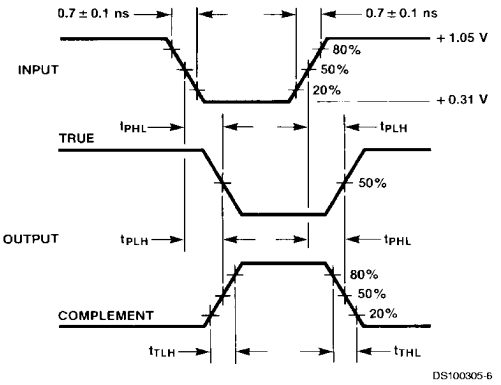
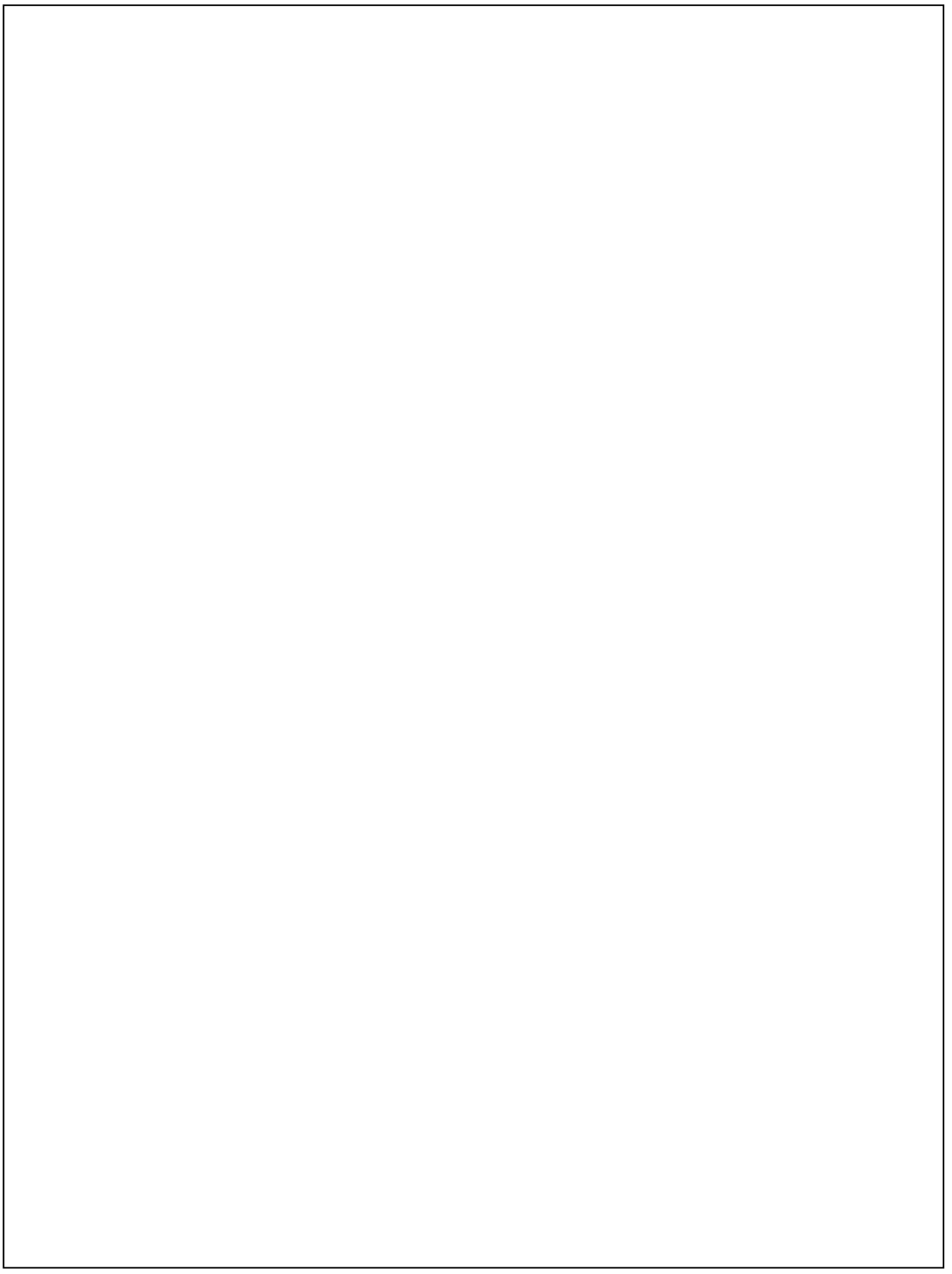
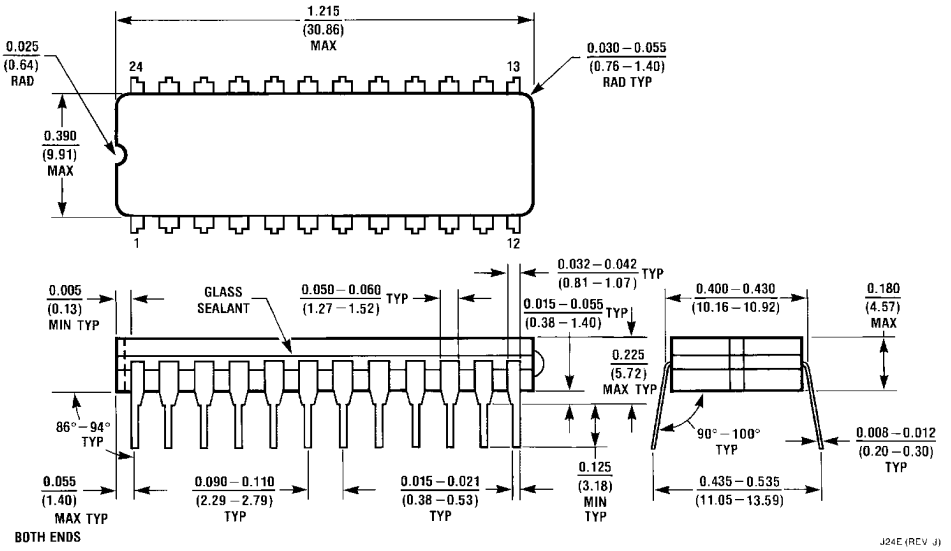


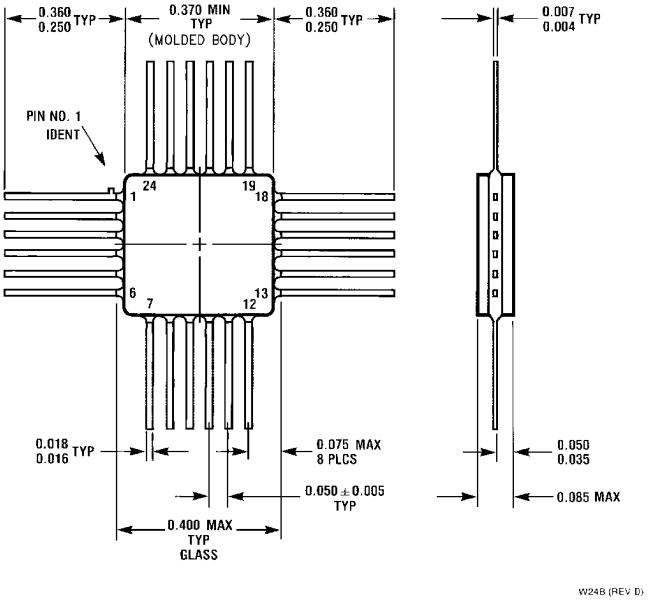
FIGURE 2. Propagation Delay and Transition Times



Physical Dimensions inches (millimeters) unless otherwise noted



24-Pin Ceramic Dual-In-Line Package (D)
NS Package Number J24E



24-Pin Quad Cerpak (F)
NS Package Number W24B